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TTM Technologies, Inc. Announces Upcoming Conference Participation

COSTA MESA, Calif., May 13, 2019 (GLOBE NEWSWIRE) -- TTM Technologies, Inc. (NASDAQ:TTMI), a leading global printed circuit board (PCB) and radio frequency (“RF”) components manufacturer, today announced that members of its management team will present at the following investor conferences:

- The J.P. Morgan Global Technology, Media and Communications Conference in Boston at the Westin Boston Waterfront Hotel on May 14, 2019 at 9:20am Eastern Time;
- The Barclays High Yield Bond and Syndicated Loan Conference in Colorado Springs, Colorado at the Broadmoor Hotel on June 6, 2019 at 11:00 am Mountain Time;
- The Stifel Cross Sector Insight Conference in Boston at the Intercontinental Hotel on June 11, 8:35am Eastern Time;
- The Nasdaq Investor Conference in London at the Mayfair Hotel on June 13, 3:00pm British Time.

The presentations will be webcast live on the company’s website, www.ttm.com, and a replay will be accessible for a limited time following the events.

About TTM

TTM Technologies, Inc. is a leading global printed circuit board manufacturer, focusing on quick-turn and technologically advanced PCBs, backplane assemblies and electro-mechanical solutions as well as a global designer and manufacturer of RF and microwave components and assemblies. TTM stands for time-to-market, representing how TTM's time-critical, one-stop manufacturing services enable customers to shorten the time required to develop new products and bring them to market. Additional information can be found at www.ttm.com.

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